

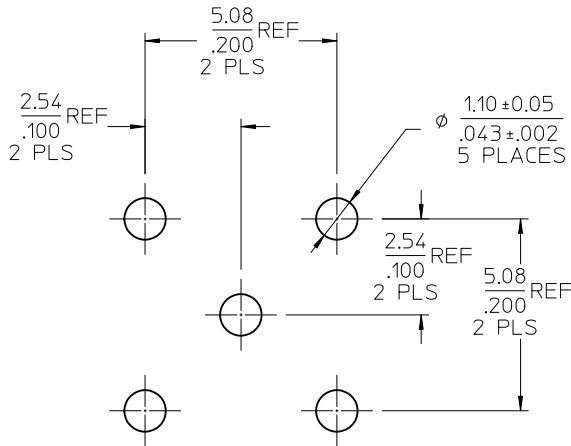
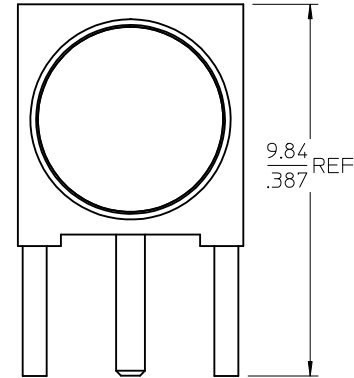
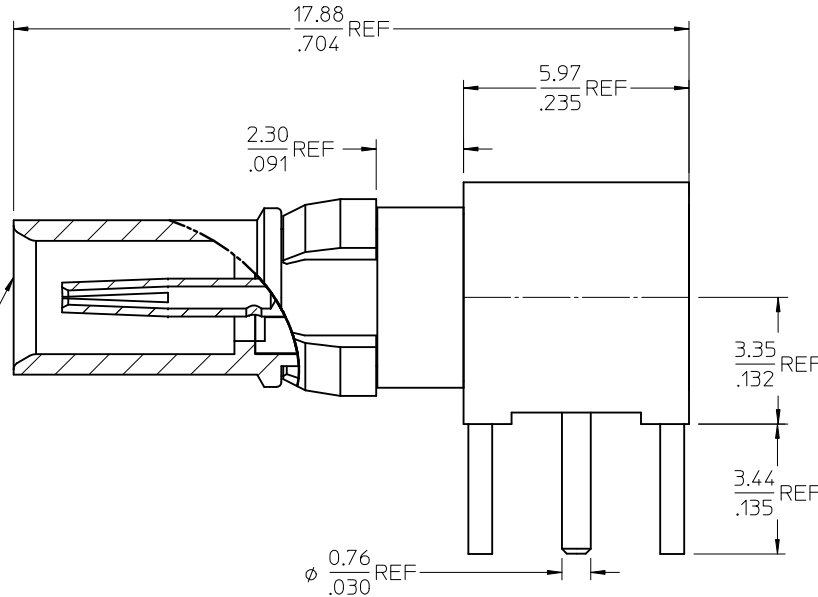
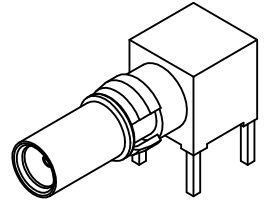
MATERIALS AND FINISHES:

BODY, CAP BRASS
PLATED GOLD

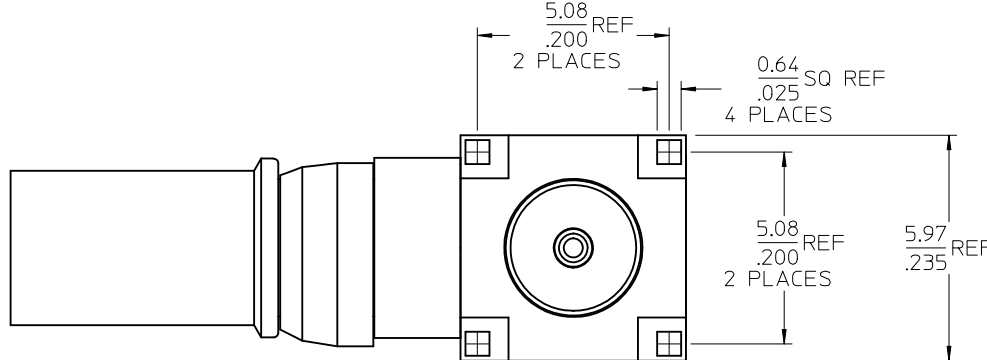
CONTACT BERYLLIUM COPPER
PLATED GOLD

INSULATOR TEFLON

RETAINING RING BERYLLIUM COPPER
PLATED NICKEL



RECOMMENDED HOLE LAYOUT



DIN 41626	INTERFACE SPECIFICATION
SPECIFICATION	DESCRIPTION

73174-0042	ONE PER BAG
73174-0040	TRAY
PART NO.	PACKAGING

CHG: ADD -0042
EC NO: URF2011-0577
DRWN: WIENER 2011/04/04
CHKD: AZR 2011/04/04
APPR: WIENER 2011/04/05

QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)
▽=0	mm INCH
▽=0	4 PLACES ± --- ± ---
	3 PLACES ± --- ± ---
	2 PLACES ± --- ± ---
	1 PLACE ± --- ± ---
	ANGULAR ± 2 °
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM/IN			METRIC	
DRAWN BY	DATE	TITLE		
TEF	2001/08/08	DIN 41626/1.0 2.3 JACK		
CHECKED BY	DATE	R/A, PCB, 50 OHM		
SSS	2001/08/08	EWR-1659 1.0/2.3-J/RA		
APPROVED BY	DATE	MATERIAL NO.		
GMH	2001/08/08	SEE TABLE		

MATERIAL NO.		DOCUMENT NO.	SHEET NO.
SEE TABLE		SD-73174-004	1 OF 1
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